

ABSTRACT**5 PUNCH SINGULATION SYSTEM AND METHOD**

A punching system for singulating IC units comprising: a punching assembly arranged to receive a substrate and singulate said substrate into the IC units; a rotary carrier rotatable from a first position to a second position said rotary
10 carrier arranged to receive said units at the first position and carry said units to the second position through rotation; wherein said rotary carrier includes recesses for receiving at least a portion of the units.

Figure 1

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